

Customer: Texas Instruments BOM REV: 1.1A
 Group: WBU-ECS EDGE: 6576620
 Board: BT-MSP-AUDSINK v1.1 Date: July 21, 2014

DNI Do Not Install

Label each bag with Part Number Board Revision and BOM Revision

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	ANT1	2.4-2.5 GHz	PCB ANTENNA	N/A	N/A		ANT_IIFA_CC2420_32MIL_MIR_1	DNI NO PART, COPPER ANTENNA ON PCB
2	6	C17, C27, C28, C29, C30, C35	0.1uF	CAP CER 0.1UF 6.3V 10% X7R 0402	KEMET	C0402C104K9ACTU		0402	
3	8	C20, C21, C24, C32, C33, C36, C39, C45	1.0uF	CAP CER 1.0UF 6.3V X5R 10% 0402	TAIYO YUDEN	JMK105BJ105KV-F		0402	
4	4	C22, C23, C46, C47	12pF	CAP CER 12PF 50V 5% NP0 0402	TDK	CGA2B2C0G1H120J050BA	GRM1555C1H120J201D	0402	
5	3	C25, C26, C41	0.47uF	CAP CER .47UF 6.3V X5R ±10% 0402	TAIYO YUDEN	JMK105BJ474KV-F		0402	
6	1	C31	22pF	CAP CER 22PF 25V 5% NP0 0201	MURATA	GRM0335C1E220JD01D		0201	
7	3	C34, C37, C42	10uF	CAP CER 10UF 4V 20% X5R 0402	TDK	C1005X5R0G106M050BB		0402	
8	2	C38, C40	22uF	CAP CER 22UF 6.3V 20% X5R 0603	TDK	C1608X5R0J226M080AC		0603	
9	2	C43, C44	2.2nF	CAP CER 2200PF 50V 10% X7R 0402	TDK	C1005X7R1H222K050BA		0402	
10	2	C48, C49	22nF	CAP CER 0.022UF 25V 10% X7R 0402	TDK	C1005X7R1E223K050BB		0402	DNI
11	1	D1	ORN	LED ORANGE 606NM 0603 SMD	OSRAM OPTO	LO L29K-J2L1-24-Z		LED_0603	
12	1	D2	YLW	LED YELLOW 587NM 0603 SMD	OSRAM OPTO	LY L29K-H1K2-26-Z		LED_0603	
13	1	D3	RED	LED SMARTLED RED 630NM 0603 SMD	OSRAM OPTO	LS L29K-H1J2-1-Z		LED_0603	
14	2	D4, D5	GRN	LED SMARTLED GREEN 570NM 0603	OSRAM OPTO	LG L29K-G2J1-24-Z		LED_0603	
15	1	FL1	2.45GHz	FILTER CER BAND PASS 2.45GHZ SMD	MURATA	LFB212G455G8C341	LFB212G455G8A127	FIL_4_85x53x41	PLACE BROWN MARKING UP CONTACT MURATA DIRECTLY FOR PART
	1	J2	MSP430 JTAG	JTAG CONNECTOR HEADER	TE CONNECTIVITY	5103308-2		TE_5103308-2	
	1	J3	LI-POL BAT HEADER	LI-ION BATTERY HEADER STD JST-PH	JST	455-1704-ND		JST_B2B-PH-K-5	MATING SOCKET 455-1165-ND
	1	J4	USB RECEPTACLE	CONN USB RCPT MINI B 5PS R/A SMD	JAE	DX2R005HN2E700		JAE_DX2R005HN2	
15	J5, J6, J7, J8, J9, J10, J11, J12, J13, J14, J15, J16, J19, J20, J21	1x2 THVT	CONN HEADER VERT 2POS .100 TIN	TE CONNECTIVITY	3-644456-2			HDR_THVT_1X2_100_M	
	1	J22	1x2 THVT	CONN HEADER VERT 2POS .100 TIN	TE CONNECTIVITY	3-644456-2		HDR_THVT_1X2_100_M	DNI
	1	J25	AUDIO PLUG	3.5MM MONO AUDIO CABLE, PLUG-WIRES, 3FT 24AWG	KOBICONN	172-1283		N/A	WHITE STRIPE WIRE TO J25 PIN 1 SOLID BLACK WIRE TO J25 PIN 2
5	J17, J18, J23, J24, J27	HEADER 1	CONN HEADER VERT .100" GOLD	TE CONNECTIVITY	5-146868-1			TP101H50	DNI
	1	J26	AA BAT HEADER	BATTERY CONNECTOR	MOLEX INC	22035035		MOLEX_22-03-5035	DNI
	3	PAD1, PAD2, PAD3	ELECTRODES	CAP-TOUCH SENSOR ELECTRODES	N/A	N/A		N/A	DNI NO PART, CAP-TOUCH PADS ON PCB
	1	P3	COAXIAL	RECEPTACLE_CON COAXIAL UFL-R-SMT	HIROSE	U.FL-R-SMT-1		HRS_U-FL-R-SMT-1	DNI
3	R1, R2, R3	2.7K	RES 2.7K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ272X			0402	
2	R4, R9	1.5K	RES 1.5K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ152X			0402	
1	R5	2.0K	RES 2K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ202X			0402	
3	R6, R7, R15	470R	RES 470 OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ471X			0402	
2	R10, R36	10K	RES 10.0K OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF1002X			0402	
1	R8	10K	RES 10.0K OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF1002X			0402	DNI
1	R11	18K	RES 18K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ183X			0402	
2	R12, R28	47K	RES 47K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ473X			0402	
10	R13, R14, R25, R26, R27, R29, R34, R35, R37, R38	OR	RES 0.0 OHM 1/10W JUMP 0402 SMD	PANASONIC	ERJ-2GE0R00X			0402	
	1	R30	OR	RES 0.0 OHM 1/10W JUMP 0402 SMD	PANASONIC	ERJ-2GE0R00X		0402	DNI
3	R31, R32, R33	75k	RES 75K OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ753X			0402	
1	SHLD1	RF SHIELD FRAME	BOARD SHIELD .65X.65" FRAME	LAIRD TECH	BMI-S-202-F			SH_BMI-S-202_650x650	DNI
1	S1	BUTTON	MSP430 RESET BUTTON	PANASONIC	EVQ-11A05R			SW_EVQ-11A05R	
2	S2, S3	POS 2 SW	SW SLIDE DPDT 6VDC 0.3A PCMNNT	C&K	JS202011CQN			SW_JS202011CQN	
1	S4	SCAN SW	SCAN SWITCH	C&K	TPC1133GLFG			SW_TPC1133G	DNI
6	TP1, TP2, TP3, TP4, TP5, TP6	TEST PAD	TP_VIA_030RND020	N/A	N/A			TP102	DNI NO PART, TEST PAD O PCB
	1	U5	CC2560BRVM	BLUETOOTH AND DUAL MODE CONTROLLER	TI	CC2560BRVMR		PVQFN_RVM_EP134X122	
	1	U7	TAS2505IRGE	DIGITAL INPUT CLASS-D SPEAKER AMPLIFIER 2W	TI	TAS2505IRGE		QFN50P400X400X100-25N	
	1	U8	TLV7101828DSE	DUAL LDO REGULATOR 1.8V 2.8V 200MA	TI	TLV7101828DSE		SON50P150X150X80-6	
	1	U9	BQ24055DSS	SINGLE CELL LI-ION BATTERY CHARGER 800MA 4.2V	TI	BQ24055DSS		SON50P300X200X80-13	
	1	U10	MSP430F5229IRGC	MSP430 16-BIT MCU 1.8V SPLIT-RAIL I/O	TI	MSP430F5229IRGC		QFN50P900X900X100-65NA	
	1	Y1	26MHz	CRYSTAL 26MHz	NDK	NX20165A (EXS00A-CS06025)	TST - TZ1325D	XTAL200X160X50	
	1	Y2	32.768KHz	CRYSTAL 32.768KHZ 12.5PF SMD	ABRACON	ABS07-32.768KHZ-T		XTAL_2_SM_130x63	
	1	Z1	MINI USB CABLE	USB 2.0 CABLE, A MALE - MINI B MALE, 3FT	QUALTEK	3021003-03G		N/A	LOOSE ITEM. INCLUDED IN KIT

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